

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn): A substrate sheet material in which a plurality of substrates to be used for producing semiconductor packages are formed, wherein an outer configuration of the substrate sheet material is made into a circular shape.

2. (Withdrawn): The substrate sheet material as claimed in claim 1, wherein a through opening is provided at a center of the substrate sheet material.

3. (Withdrawn): The substrate sheet material as claimed in claim 1, wherein at least one through hole is provided in an area other than an area where the substrates are formed.

4. (Withdrawn): The substrate sheet material as claimed in claim 3, wherein a plurality of the through holes are provided and arranged along a circumference of the area where the substrates are formed.

5. (Withdrawn): A substrate sheet material in which a plurality of substrates to be used for producing semiconductor packages are formed, wherein at least one through hole is provided outside an area where the substrates are formed and within an area where a resin mold is formed.

6. (Withdrawn): The substrate sheet material as claimed in claim 5, wherein a plurality of the through holes are provided and arranged along a circumference of the area where the substrates are formed.

7. (Currently amended): A mold method of a substrate sheet material, comprising:
preparing a circular substrate sheet material in which a plurality of substrates are formed;

mounting a semiconductor chip onto each of the substrates; and

resin-molding the semiconductor chips all at once; and wherein at least one opening is formed in said circular substrate sheet material and a mold resin is filled into a cavity of a mold die through said at least one opening.

8. (Currently amended): The mold method as claimed in claim 7, wherein ~~[[an]]~~ said opening is formed at a center of the circular substrate sheet, ~~and a mold resin is filled into a cavity of a mold die through the opening.~~

9. (Currently amended): The mold method as claimed in claim 7, further comprising;

forming at least one through hole at said at least one opening outside an area where the substrate are formed and within an area where a resin mold is formed; and

supplying a mold resin to a backside of the substrate sheet material opposite to a front side where the semiconductor chips are mounted so as to form a resin part on the backside.

10. (Original): The mold method as claimed in claim 9, comprising:

forming a plurality of the through holes along a circumference of a resin part formed on the surface of the substrate sheet material;

supplying the mold resin to the backside through the plurality of through holes;

and

forming on the backside a resin part having a shape along the resin part formed on the front side.

11. (Original): A mold method of a substrate sheet material comprising:

preparing a substrate sheet material in which a plurality of substrates are formed, the substrate sheet material having at least one through hole outside an area where the substrates are formed and within an area where a resin mold is formed;

mounting a semiconductor chip onto each of the substrate of the substrate sheet material;

molding the mounted semiconductor chips all at once; and

introducing a mold resin through the through hole into a backside of the substrate sheet material opposite to a front side on which the semiconductor chips are mounted so as to form a resin part on the backside.

12. (Original): The mold method as claimed in claim 11, comprising:

forming a plurality of the through holes along a circumference of the resin part
formed on the front side of the substrate sheet material;

supplying the mold resin to the backside through the plurality of through holes;

and

forming on the backside of the substrate sheet material a resin part having a shape
along the resin part formed on the front side of the substrate sheet material.

13. (Currently amended): A manufacturing method of a substrate sheet material
for manufacturing substrates all at once, the substrates used for manufacturing semiconductor
packages, the method comprising:

preparing a sheet material having a circular outer configuration; and

forming a circular substrate sheet material by forming wiring on the sheet material
and forming a plurality of substrates in the sheet material; and,

wherein at least one opening is formed in said circular substrate sheet material and a mold
resin is filled into a cavity of a mold die through said at least one opening.

14. (Withdrawn): A manufacturing method of a substrate sheet material for
manufacturing substrates all at once, the substrates used for manufacturing semiconductor
packages, the method comprising:

preparing a sheet material having a quadrate outer configuration;

forming wiring on the sheet material and forming a plurality of substrates in the
sheet material; and

forming a circular substrate sheet material by cutting the sheet material having the plurality of substrates in a circular shape.

15. (Currently amended): A manufacturing method of semiconductor devices, comprising:

preparing a circular substrate sheet material in which a plurality of substrates are formed, the substrates used for producing semiconductor packages;

mounting a semiconductor chips onto each of the substrates of the circular substrate sheet material;

molding the semiconductor chips on the substrate sheet material all at once so as to form the semiconductor packages corresponding to the respective substrates; ~~and~~

individualizing the semiconductor packages; and wherein at least one opening is formed in said circular substrate sheet material and a mold resin is filled into a cavity of a mold die through said at least one opening.

16. (Currently amended): The manufacturing method of semiconductor devices as claimed in claim 15, wherein said opening is a through opening part ~~[[is]]~~ formed at a center of the substrate material.

17. (Currently amended): The manufacturing method of semiconductor devices as claimed in claim 15, wherein said opening is a at least one through hole ~~[[is]]~~ formed outside an area where the substrates are formed and within an area where a resin mold is formed.

18. (Original): The manufacturing method of semiconductor devices as claimed in claim 17, wherein a plurality of the through holes are formed along a circumference of the area where the substrates are formed.

19. (Original): A manufacturing method of semiconductor devices, comprising:
preparing a substrate sheet material in which a plurality of substrates used for producing the semiconductor devices are formed and at least one through hole is provided in an area other than an area where the substrates are formed;

mounting a semiconductor chip onto each of the substrates off the substrate sheet material;

resin-molding the mounted semiconductor chips all at once;

introducing a mold resin through the through hole into a backside of the substrate sheet material opposite to a front side on which the semiconductor chips are mounted so as to form a resin part on the backside;

forming semiconductor packages corresponding to the respective substrates; and
individualizing the semiconductor packages.

20. (Original): The manufacturing method of semiconductor devices as claimed in claim 19, comprising:

forming a plurality of the through holes along a circumference of the resin part formed on the front side of the substrate sheet material;

supplying the mold resin to the backside of the substrate sheet material through the plurality of through holes; and

forming on the backside of the substrate sheet material a resin part having a shape along a circumference of the resin part formed on the front side.

21. (Currently amended): A manufacturing method of semiconductor devices, comprising:

preparing a circular semiconductor manufacturing material having a principal surface on which a plurality of electronic parts are formed;

immersing the semiconductor manufacturing material into a dissolved resin;

curing the dissolved resin; and cutting the semiconductor manufacturing material and the resin part on the principal surface together so as to separate into a plurality of resin coated chip-like electronic parts;

wherein only said principal surface is immersed in said dissolved resin.